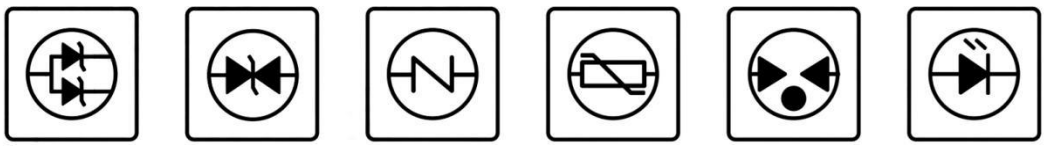
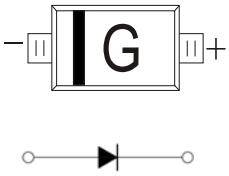
MSKSEMI
SEMICONDUCTOR



Product data sheet

SOD-523

MARKING: G



1SS387 High Speed Switching Diode

FEATURES

- Small surface mounting type
- High speed
- High reliability with high surge current handing capability

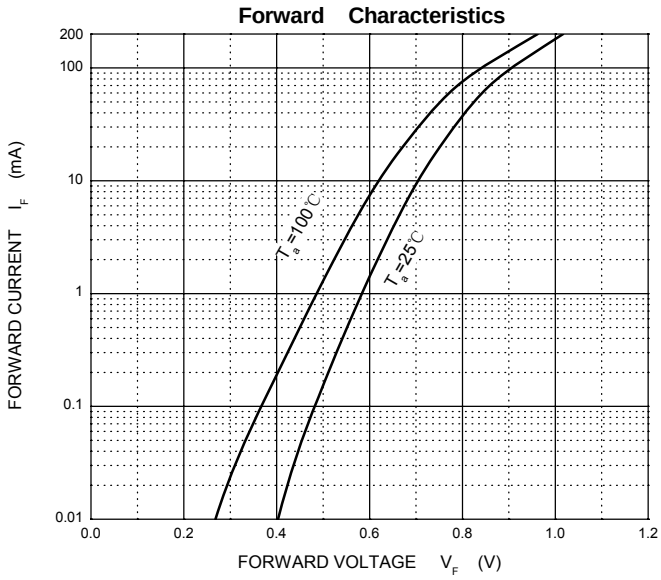
Maximum Ratings and Electrical Characteristics, Single Diode @Ta=25℃

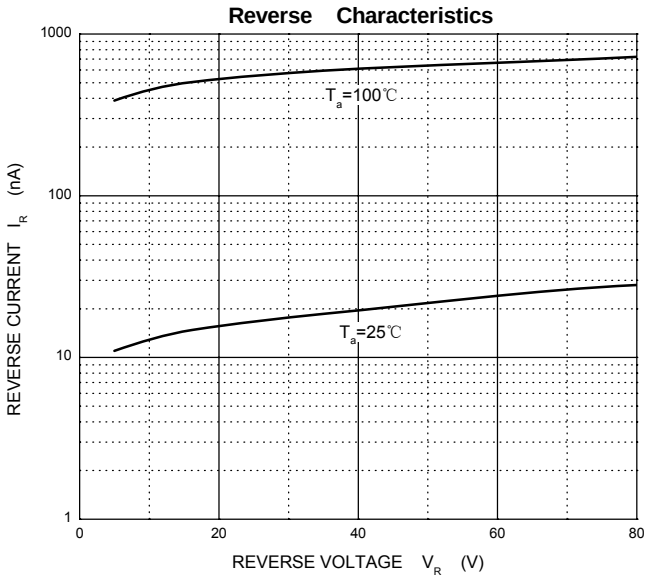
Parameter	Symbol	Limit	Unit
Non-Repetitive Peak Reverse Voltage	V_{RM}	85	V
DC Blocking Voltage	V_R	80	V
Forward Continuous Current	I_{FM}	200	mA
Average Rectified Output Current	I_O	100	mA
Non-Repetitive Peak Forward Surge Current @t=8.3ms	I_{FSM}	2.0	A
Power Dissipation	Pd	150	mW
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	833	℃/W
Junction Temperature	T_j	150	℃
Storage Temperature	T_{STG}	-55~+150	℃

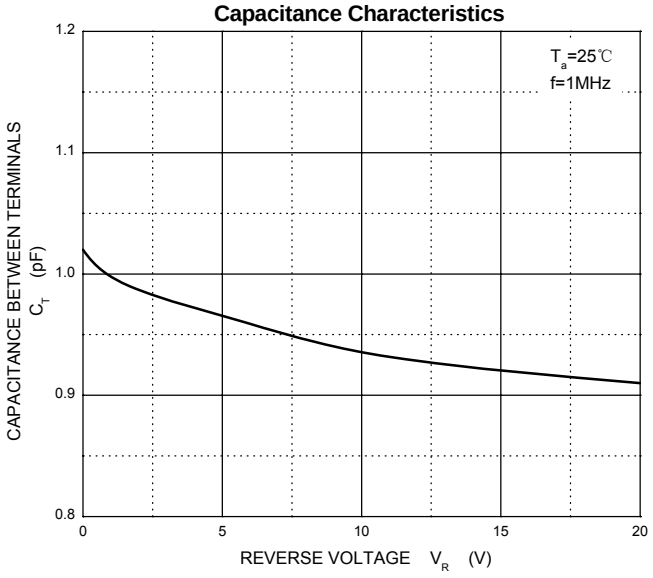
Electrical Ratings @Ta=25℃

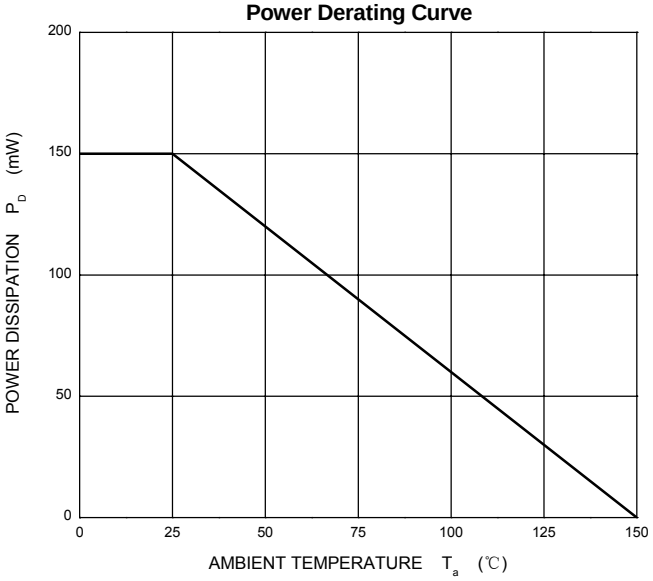
Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V_{F1}		0.62		V	I_F=1mA
	V_{F2}		0.75		V	I_F=10mA
	V_{F3}			1.2	V	I_F=100mA
Reverse current	I_{R1}			0.1	μA	V_R=30V
	I_{R2}			0.5	μA	V_R=80V
Capacitance between terminals	C_T			3.0	pF	V_R=0,f=1MHZ
Reverse recovery time	t_{rr}			4	ns	V_R=6V,I_F=10mA,R_L=100Ω

Typical Characteristics

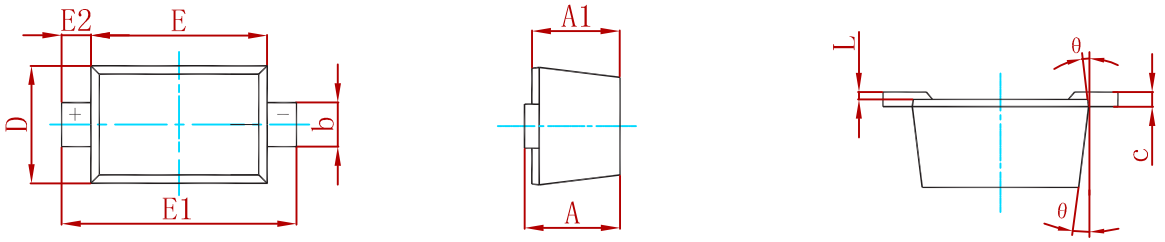






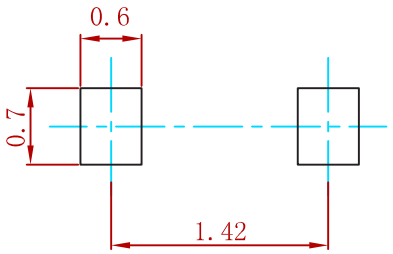


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.510	0.770	0.020	0.031
A1	0.500	0.700	0.020	0.028
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	0.750	0.850	0.030	0.033
E	1.100	1.300	0.043	0.051
E1	1.500	1.700	0.059	0.067
E2	0.200 REF		0.008 REF	
L	0.010	0.070	0.001	0.003
θ	7° REF		7° REF	

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
1SS387	SOD-523	3000

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